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Prodrive Technologies at a glance

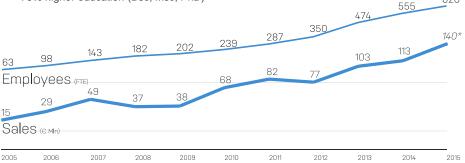


One of the fastest growing privately owned technology companies in Europe

We focus on autonomous growth and a solid preservation of our company culture

Current state

- ▶ 610 FTE of which 330 in development
- ▶ 70% higher education (Bsc, Msc, PhD)



Core Business

- Design of electronics, software and mechanics
- Manufacturing
- Added value services

Business model

- Ready-to-use products
- Technology solutions
- Manufacturing services



* Forecasted sales















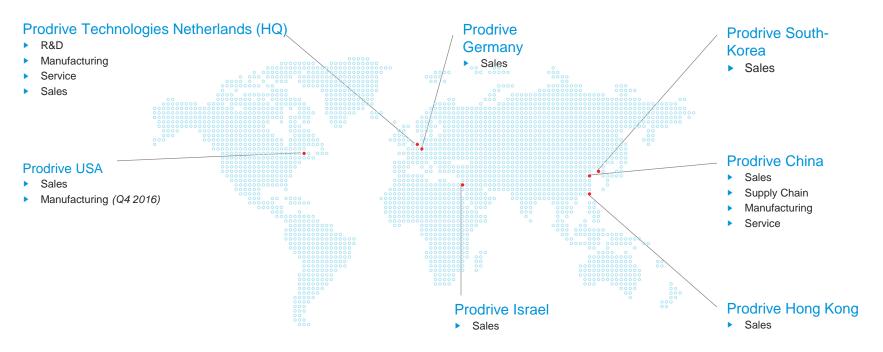






A global reach

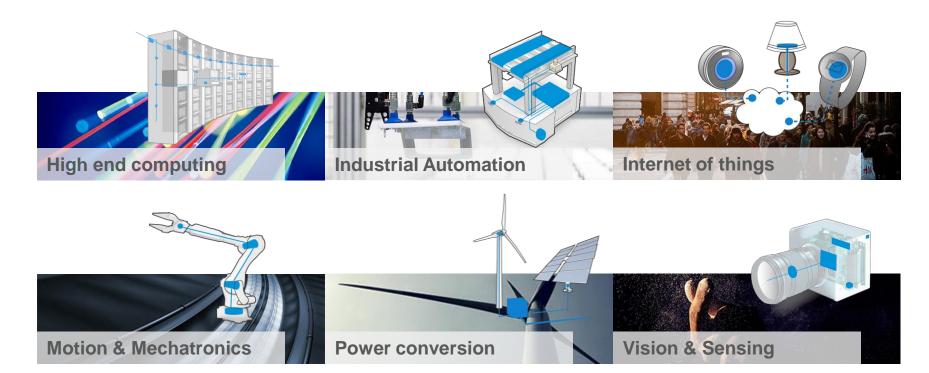




• Prodrive Technologies footprint to facilitate local demand

Our technologies





High-End Computing (HEC)



HEC solutions

- Consist of a number of systems-on-chip with dedicated memory, interconnected by buses and/or packet switched networks
- May be heterogeneous
- May be scalable
- May be subjected to hard real-time constraints

Innovation

- Addressing the market's next needs
- ▶ Performance / \$
- ▶ Performance / Watt
- ▶ Performance / m3













HEC examples

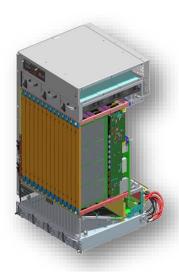
PRODRIVE

Massively parallel high-end image processing

- ▶ Optical incoming data >160GB/s
- ► 2x ATCA shelf per cabinet
- ▶ RapidIO & 10/40GbE switching
- ▶ 576 ARM A15 MPCores
- ▶ 3456 C66x DSP CorePacs
- ► FPGA frame grabbing
- ▶ ±2 TB DDR memory

Water cooling







HEC examples



Wafer lithography

- ▶ 50kHz motion control loop; Going to 100kHz
 - ▶ 20us (10us) for processing and communication
- ▶ 14nm lithography, going to <10 nanometer
- ▶ RapidIO & 10/40GbE switching
- PowerPC processing
- FPGA synchronization and co-processing
- ▶ Intel x86 server, Host and co-processing
- ▶ 200kW power supply
- Multi-kW high-accuracy power amplifiers
 - RapidIO driven
- Water cooling







Heterogeneous Computing: building blocks

Intel Xeon processing



Intel® Broadwell-DE® SoC

- 5th generation Xeon on 14nm process
 - 2.1x more efficient than 4th gen
- 10GbE Ethernet
- PCle 3.0 x24 / PCle 2.0 x8
- Optionally 2x 20Gbps Serial RapidIO

Platform options

- Scalable 2, 4 or 8 cores (<20W ~ 45W)
- SATA 3.0 / USB 3.0
- 7 yr life/10 yr reliability with high Tcase

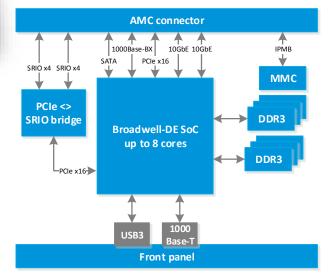
Compliance

- PICMG AMC.0 R2.0
- PICMG AMC.2 R1.0
- PICMG AMC.4 R1.0
- PICMG MTCA.0 R1.0

Applications

- Image processing
- Dense HPC
- Micro servers
- Storage





Status: Prototype 2015Q3

7-series FPGA platform



Feature	AMC-XZ7	AMC-XV7	
FPGA	125K – 350K logic cells (Zynq-7000)	320K – 690K logic cells (Virtex-7)	
DDR FPGA	Up to 8GB, 1600MT/s, ECC	Up to 16GB, 1600MT/s, ECC	
ARM	2x ARM Cortex-A9		
Interconnect support	Serial RapidIO 2.1 (Up to 20GBaud / por Serial RapidIO 3.x prepared (Up to 40GBaud / por 10GBASE-KR (Up to 10GBaud / por 1000BASE-T (Up to 1GBaud / port)		
AMC connector ports	1x Gigabit Ethernet 2x single lane Up to 1x quad lane	1x Gigabit Ethernet 1x 10Gb Ethernet Up to 2x quad lane	
Front panel ports	1x RJ-45 2x SFP+	1x RJ-45 2x QSFP+	
Flash	Up to 128MB NOR, 8GB eMMC	Up to 128MB NOR	
AMC width	Single		
AMC height	Full-size, Mid-size		
ммс	Pigeon Point 1.5 based		
Applicable standards	PICMG AMC.0 R2.0 PICMG AMC.x R1.0		







ARM+DSP platform



Feature	AMC-TK2	AMC-TK2-H2S	
ARM core	4x A15 MPCore, 1.4GHz		
DDR ARM	Up to 2GB DDR3, 1333MT/s, ECC		
DSP core	8x C66x CorePac, 1.2GHz	24x C66x CorePac, 1.2GHz	
DDR DSP	Up to 8GB DDR3, 1333MT/s, ECC	Up to 24GB DDR, 1333MT/s, ECC	
Serial RapidIO	2.1 (up to 5Gbaud)		
SRIO to AMC connector	1x	3x	
1GbE to AMC connector	1x 1000Base-BX		
10GbE to AMC connector	1x 10GBase-KR		
Ethernet to front panel	1x 1000Base-T		
RS232	1x CPU, 1x MMC		
Flash	64MB NOR	192MB NOR	
AMC width	Single		
AMC height	Full-size		
ММС	Pigeon Point 1.5 based		
Applicable standards	PICMG AMC.0 R2.0 PICMG AMC.x R1.0		





ATCA-TK2-6PU: High density ARM+DSP



6x processing units (PUs) in 1 ATCA blade

- 1 PU = AMC-TK2-H2S, without AMC mechanics
- 512MB DDR per ARM / DSP core; 84GB per blade

Connectivity

- Switched 10/40GbE (PUs, Zone-2, Zone-3)
- Switched Serial RapidIO Gen. 2 (PUs, Zone-3)
- Point-to-point PCIe Gen. 2 (PUs, Zone-3)
- 1GbE within PU
- 2x HyperLink (up to 40GBaud) within PU

Supports application specific RTM

- Switched RapidIO / Ethernet
- Point-to-point PCIe









Status: Prototype 2015Q1

PowerPC platform



Feature	AMC-FP3-8548	AMC-FQP-4080	AMC-FQP-5020
PowerPC core	1x e500v2, 1.3GHz	8x e500mc, 1.5GHz	2x e5500, 2.1GHz
DDR	1GB DDR2, 533MT/s, ECC	R2, 533MT/s, ECC Up to 16GB DDR3, 1333MT/s, ECC	
Serial RapidIO	1.2 (up to 3.125Gbaud)		1.3 (up to 5Gbaud)
SRIO to AMC connector	1x	2x	
1GbE to AMC connector	1x 1000Base-BX		
Ethernet to front panel	1x 1000Base-T		
SATA	No		2x 3Gbps
RS232	1x CPU, 1x MMC		
Flash	8MB NOR		
AMC width	Single		
AMC height	Full-height, Mid-height		
MMC	Pigeon Point 1.5 based		
Applicable standards	PICMG AMC.0 R1.0 PICMG AMC.2 R1.0 PICMG AMC.4 R1.0	PICMG AMC.0 R1.0 PICMG AMC.2 R1.0 PICMG AMC.4 R1.0 PICMG MTCA.0 R1.0	PICMG AMC.0 R1.0 PICMG AMC.2 R1.0 PICMG AMC.3 R1.0 PICMG AMC.4 R1.0 PICMG MTCA.0 R1.0







ATX-KM-4M256: Quad MPPA-256 PCIe card



Quad MPPA-256

- 4x KALRAY Multi-Purpose Processing Array
- Up to 16GB DDR3, 1600MT/s, ECC (SODIMM)
- Up to 256MB NOR flash

Connectivity

- 10Gbps Network-on-Chip eXtension (NOCX)
- Switched PCIe Gen. 3 x16 (MPPA, PCIe connector)
- 2x FireFly system connectors
- 1/10/40Gb Ethernet
- Interlaken

ATX, PCIe x16





Status: Production 2015Q3



Enabling Heterogeneous Computing

Switching, interconnects & infrastructure

Introducing RapidIO



- Bandwidth
- Low switch latency
- Free topology
- Low TCO (Gbps/\$, Gbps/W)
- Scales to 1000s of nodes
- Protocol termination in hardware
- Guaranteed delivery
- Direct memory access, interrupts
- Messaging
- Real-time characteristics

- = like Ethernet
- = like PCle
- = like Ethernet
- = like PCle
- = like Ethernet
- = like PCle
- = like PCle
- = like PCle
- = like Ethernet
- = unheard of

HPC2.0



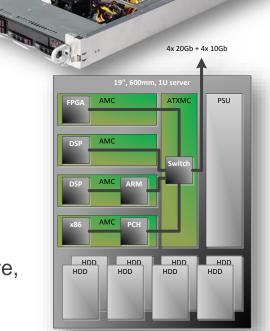
Datacenter and Compute Platform: 4 AMC-slot

- Up to 4 AMCs
- 160Gbps RapidIO to AMCs; 80Gbps RapidIO to back
- 4x 10GbE to daughter cards
- Easily customizable

Datacenter and Compute Platform: 8 AMC-slot

- Up to 8 AMCs
- Switched RapidIO Gen2 20Gbps per port
- Switched 10GbE/40GbE
- High performance density and heterogeneous computing in 1U

Wide Choice of cards: x86, ARM, DSP, FPGA, PowerPC, Manycore, GPU, Storage (SATA, NVMe)



Top-of-Rack RapidIO switch



38-port, 19" Serial RapidIO Gen. 2 switch box

- 32 QSFP+ (20Gbps/port)
- 2 CXP (60Gbps/port)
- 2.4Tbps non-blocking bandwidth
- Integrated host controller
- 150W TDP (est.)
- 8x switched GbE

Latency: 100ns-300ns

Power (est): <4W per port, <0.1W per Gbps







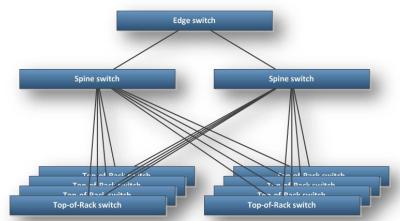
Status: Prototype 2015Q2

Top-of-Rack RapidIO switch

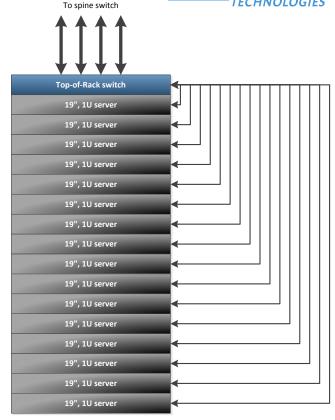
En-masse aggregation of pizzas
ToR switches for scale-out

- Within rack
- Between racks

Spine switches and edge switches







AdvancedTCA RapidIO switching

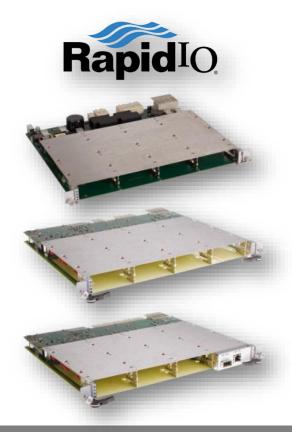


ATCA RapidIO carrier & switch blades

- 3x or 4x full-size AMC support
- 320Gbps or 560Gbps non-blocking RapidIO gen2
 - 2x per AMC
 - ► 6x or 16x to backplane
- Gigabit Ethernet
 - 1x per AMC
 - 6x or 16x to backplane

ATCA RapidIO carrier blade

- 4x full-height AMC support
- 160Gbps non-blocking RapidIO gen1
 - 2x per AMC
 - 4x to backplane
- Gigabit Ethernet
 - 1x per AMC
 - 5x to backplane



AdvancedTCA 10/40Gb Ethernet switching



Ethernet ATCA carrier & switch blades

- Trident based, up to 640GbE non-blocking
- Up to 13x 10/40GBASE-KR to backplane
- Up to 13x 10/1000/1000BASE-T to backplane
- Up to 8x SFP+/2x QSFP+ cages on front panel

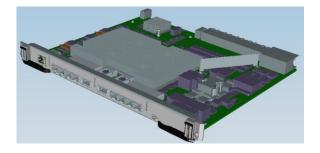
Greyhound building block

- 1/10GbE 16-port switch with ARM
- Fit to integrate on existing products or standalone
- Up to Layer-3 switching (QoS / AVB / TSB)

FPGA 10G UDP IP core

- Based on Xilinx 10GbE stack
- Forward Error Correction (FEC)





Status: Prototype 2015Q2

Concluding



- Heterogeneous Computing proven in mission critical solutions
- Focus on performance/W and performance/m3 is key
- RapidIO enables large scale heterogeneous computing, while not disabling Ethernet
- Next generation coming soon!

Quality matters

Continuous improvement



ISO 9001:2008 Quality management

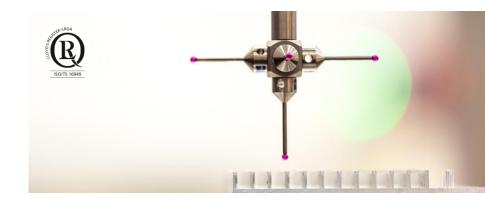
ISO 13485:2012 Quality management – medical devices

ISO 14001:2004 Environmental management
OHSAS 18001:2008 Health and safety management

IECEE CB Scheme Certified WMT laboratory

ISO/TS 16949:2009 Automotive quality management system

ISO/IEC17025:2005 Accreditation in progress



Information Systems Roadmap

Building a world class information system that provides real time information to the entire organization (e.g. KPI's, SPC, Performance dashboards)

Operations Roadmap

Continually reducing manual labor by robotics and automation (e.g. automatic guided vehicles, smart feeder carts, an automated warehouse)

Management System Roadmap

Continually improve our quality, health, environmental and safety performance





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